



A Product Line of Diodes Incorporated

ZXGD3006E6

40V 10A GATE DRIVER IN SOT26

Description

ZXGD3006E6 is a 40V Gate Driver for switching IGBTs and SiC MOSFETs. It can transfer up to 10A peak source/sink current into the gate for effective charging and discharging of a large capacitive load.

The ZXGD3006E6 can drive typically 4A into the low gate impedance of an IGBT, with just 1mA input from a controller. Also, the turn-on and turn-off switching behavior of the IGBT can be individually tailored to suit an application. In particular, by defining the switching characteristics appropriately, EMI and cross conduction problems can be reduced.

Applications

Gate driving IGBTs and SiC MOSFETs in:

- Solar inverters
- Power supplies
- Plasma display panel power modules
- DC-DC converters in electric cars

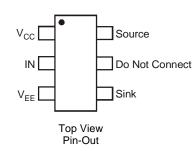
Features

- High-gain buffer with typically 4A output from 1mA input
- 40V supply for +20V to -18V gate driving to prevent dV/dt induced false triggering
- Emitter-follower that is rugged to latch-up / shoot-through issues, and delivers <10ns propagation delay time
- Separate source and sink outputs for independent control of IGBT turn-on and turn-off times
- Optimized pin-out to simplify PCB layout and reduce parasitic trace inductances
- Near-zero quiescent supply current
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP capable (Note 4)

Mechanical Data

- Case: SOT26
- Case material: molded plastic. "Green" molding compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 ³
- Weight: 0.018 grams (approximate)





| Pin Name | Pin Function |
|-----------------|-----------------------|
| V _{CC} | Supply voltage high |
| IN | Driver input pin |
| V _{EE} | Supply voltage low |
| SOURCE | Source current output |
| SINK | Sink current output |

Ordering Information (Notes 4 & 5)

| Product | Compliance | Marking | Reel size (inches) | Tape width (mm) | Quantity per reel |
|---------------|------------|---------|--------------------|-----------------|-------------------|
| ZXGD3006E6TA | AEC-Q101 | 3006 | 7 | 8 | 3000 |
| ZXGD3006E6QTA | Automotive | 3006 | 7 | 8 | 3000 |

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
 Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.

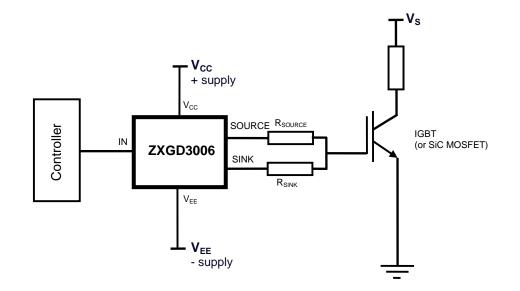
5. For packaging details, go to our website at http://www.diodes.com

Marking Information





Typical Application Circuit



| Maximum Ratings (@T _A = +25°C, unless otherwise specified.) | | | | |
|--|----------------------------|-------|------|--|
| Characteristic | Symbol | Value | Unit | |
| Supply voltage, with respect to V _{EE} | V _{CC} | 40 | V | |
| Input voltage, with respect to V _{EE} | VIN | 40 | V | |
| Output difference voltage (Source – Sink) | $\Delta V_{(source-sink)}$ | ±7.5 | V | |
| Peak output current | I _{PK} | ±10 | A | |
| Input current | l _{IN} | ±100 | mA | |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | |
|---|----------------------------------|-------------|-------|--|
| Power Dissipation (Notes 6 & 7) | P | 1.1 | W | |
| Linear derating factor | PD | 8.8 | mW/°C | |
| Thermal Resistance, Junction to Ambient (Notes 6 & 7) | R _{θJA} | 113 | °C/W | |
| Thermal Resistance, Junction to Lead (Note 8) | R _{θJL} | 105 | | |
| Operating and Storage Temperature Range | T _{J,} T _{STG} | -55 to +150 | °C | |

6. For a device surface mounted on 25mm x 25mm x 0.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition. The heatsink is split in half with the pin 1 (V_{CC}) and pin 3 (V_{EE}) connected separately to each half.
7. For device with two active die running at equal power.
8. Thermal resistance from junction to solder-point at the end of each lead on pin 1 (V_{CC}) and pin 3 (V_{EE}). Notes:

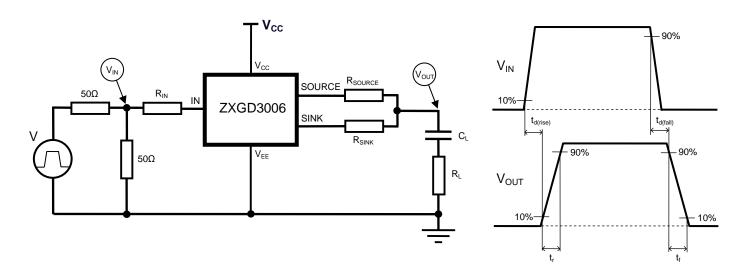


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ZXGD3006E6

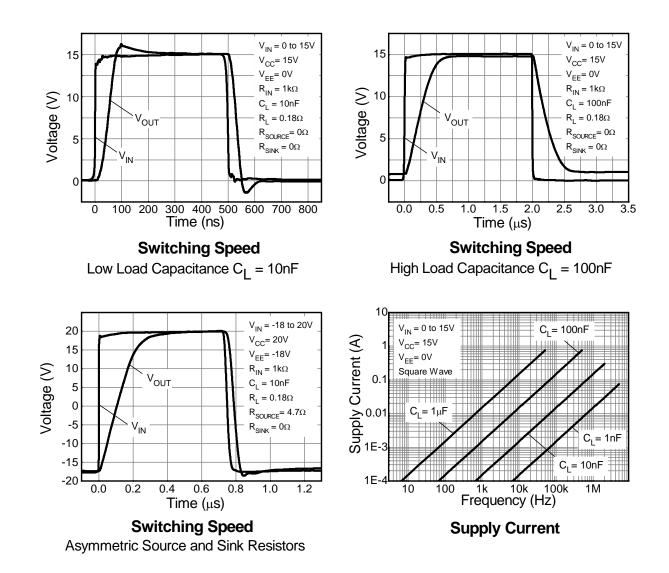
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|--|--|-----------|----------------------------------|-----------------------|------|--|
| Output voltage, high | Vout(hi) | Vcc - 1.0 | V _{CC} - 0.8 | - | V | $V_{IN} = V_{CC}$ $C_L = 1nF$ |
| Output voltage, low | V _{OUT(low)} | - | $V_{EE} + 0.12$ | V _{EE} + 0.3 | v | $V_{IN} = V_{EE}$ $R_{SOURCE} = 0\Omega, R_{SINK} = 0\Omega$ |
| Supply breakdown voltage | BVcc | 40 | - | - | V | $I_Q = 100\mu A$, $V_{IN} = V_{CC}$ |
| Supply bleakdown voltage | DVCC | 40 | - | - | v | $I_Q = 100 \mu A, V_{IN} = V_{EE} = 0 V$ |
| Quiescent supply current | lq | - | - | 50 | nA | $V_{CC} = 30V, V_{IN} = V_{CC}$ |
| | ιQ | - | - | 50 | ПА | V_{CC} = 30V, V_{IN} = V_{EE} = 0V |
| Source current | I _(source) | - | 4.0 | - | А | V_{CC} = 5V, I _{IN} = 1mA, V_{OUT} = 0V |
| Sink current | I _(sink) | - | 3.8 | - | Λ | V _{CC} = 5V, I _{IN} =-1mA, V _{OUT} = 5V |
| Source current with varying input resistances | I _(source) | - | 6.4 5.5 3.9 2.2 0.44 | - | A | $ \begin{array}{l} R_{IN}=200\Omega \\ R_{IN}=1k\Omega \\ R_{IN}=10k\Omega \\ R_{IN}=100k\Omega \\ R_{IN}=1000k\Omega \end{array} \\ \begin{array}{l} V_{CC}=15V, \ V_{EE}=0V \\ V_{IN}=15V \\ C_{L}=100nF, \ R_{L}=0.18\Omega \\ R_{SOURCE}=0\Omega, \ R_{SINK}=0\Omega \end{array} $ |
| Sink current with varying input resistances | l(sink) | - | 7.7 6.5 4.4 2.3 0.46 | - | A | $ \left \begin{array}{l} R_{IN} = 200\Omega \\ R_{IN} = 1k\Omega \\ R_{IN} = 10k\Omega \\ R_{IN} = 100k\Omega \\ R_{IN} = 1000k\Omega \end{array} \right V_{CC} = 15V, \ V_{EE} = 0V \\ V_{IN} = 15V \\ C_L = 100nF, \ R_L = 0.18\Omega \\ R_{SOURCE} = 0\Omega, \ R_{SINK} = 0\Omega \\ \end{array} $ |
| Switching times with low load capacitance $C_L = 10nF$ | t _{d(rise)} t _r t _{d(fall)} t _f | - | 8 48 16 35 | - | ns | $\begin{split} V_{CC} &= 15V, \ V_{EE} = 0V \\ V_{IN} &= 0 \ to \ 15V \\ R_{IN} &= 1k\Omega \\ C_L &= 10nF, \ R_L = 0.18\Omega \\ R_{SOURCE} &= 0 \ \Omega, \ R_{SINK} = 0 \ \Omega \end{split}$ |
| Switching times with high load capacitance $C_L = 100nF$ | t _{d(rise)} t _r t _{d(fall)} t _f | - | 46 419 47 467 | - | ns | $\begin{split} V_{CC} &= 15V, \ V_{EE} = 0V \\ V_{IN} &= 0 \ to 15V \\ R_{IN} &= 1k\Omega \\ C_L &= 100nF, \ R_L = 0.18\Omega \\ R_{SOURCE} &= 0\Omega, \ R_{SINK} = 0\Omega \end{split}$ |
| Switching times with asymmetric source and sink resistors | t _{d(rise)} t _r t _{d(fall)} t _f | - | 27 208 11 53 | - | ns | $V_{CC} = 20V, V_{EE} = -18V$ $V_{IN} = -18 \text{ to } 20V$ $R_{IN} = 1k\Omega$ $C_L = 10nF, R_L = 0.18\Omega$ $R_{SOURCE} = 4.7\Omega, R_{SINK} = 0\Omega$ |

Switching Test Circuit and Timing Diagram



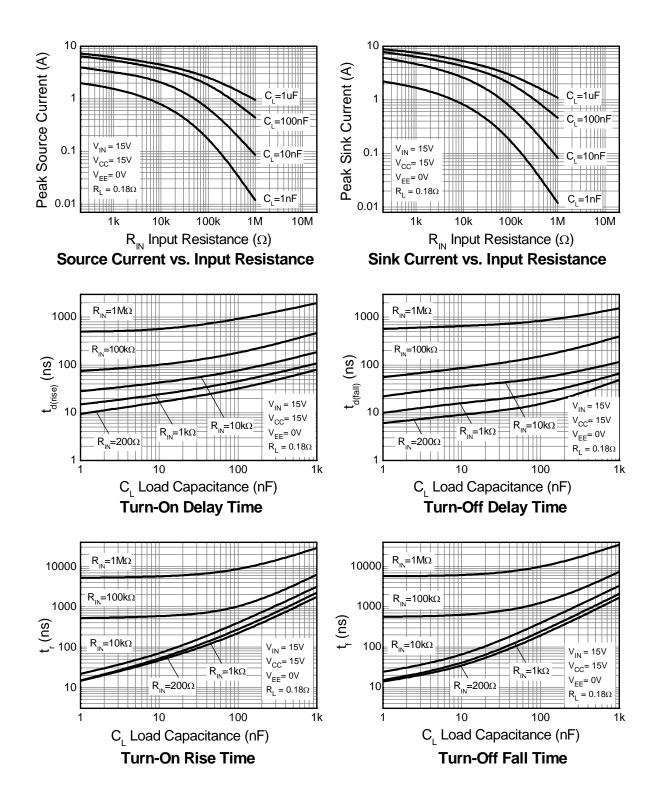


Typical Switching Characteristics (@T_A = +25°C, unless otherwise specified.)



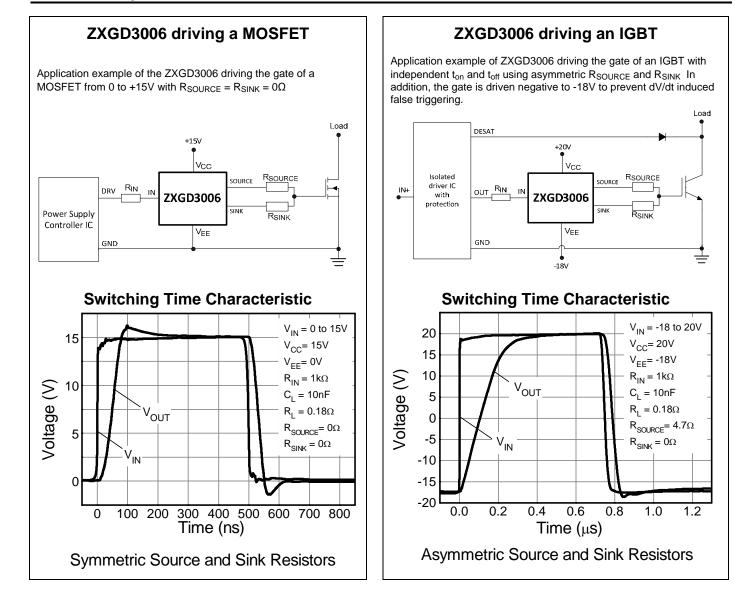


Typical Switching Characteristics (@T_A = +25°C, unless otherwise specified.)





Circuit Examples

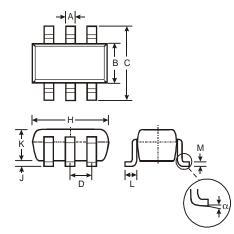




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Package Outline Dimensions

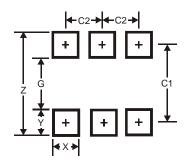
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



| SOT26 | | | | |
|----------------------|-------|------|------|--|
| Dim | Min | Max | Тур | |
| Α | 0.35 | 0.50 | 0.38 | |
| в | 1.50 | 1.70 | 1.60 | |
| С | 2.70 | 3.00 | 2.80 | |
| D | _ | | 0.95 | |
| Н | 2.90 | 3.10 | 3.00 | |
| J | 0.013 | 0.10 | 0.05 | |
| Κ | 1.00 | 1.30 | 1.10 | |
| L | 0.35 | 0.55 | 0.40 | |
| М | 0.10 | 0.20 | 0.15 | |
| α | 0° | 8° | | |
| All Dimensions in mm | | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 3.20 |
| G | 1.60 |
| Х | 0.55 |
| Y | 0.80 |
| C1 | 2.40 |
| C2 | 0.95 |



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